

PACKAGE ASSEMBLY FOR ELECTRONIC DEVICE AND METHOD OF MAKING
SAME

ABSTRACT OF THE DISCLOSURE

A buffer layer is formed on a substrate and then electronic devices are packed on the buffer layer in the present invention, and problems of lower hermeticity and complex process in the conventional arts can be avoided. Therefore, the present invention provides a packaging structure and method with a better hermeticity and a simpler process. Especially, due to the buffer layer, the planarization for flip-chip bonding can be improved and reduce negative effects of the packing process.